

MOSFET Silicon N-Channel MOS

1. Applications

Soft Switching Boost PFC switch, Half bridge or Asymmetric half bridge or Series resonance half bridge and full bridge topologies.

Such as phase-shift-bridge(ZVS),LLC Application-Server Power, Telecom Power, EV Charging,Solar inverter.



2. Features

Low drain-source on-resistance: $R_{DS(ON)} = 1.24\Omega$ (typ.)

Easy to control Gate switching

Enhancement mode: $V_{th} = 2.5$ to 4.5 V

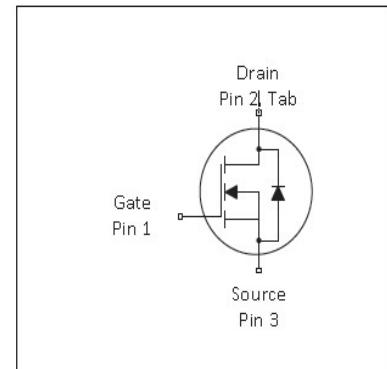


Table 1 Key Performance Parameters

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	700	V
$R_{DS(on),max}$	1.4	Ω
$Q_{g,typ}$	5.76	nC
$I_{D,pulse}$	12	A

3. Packaging and Internal Circuit

Part Name	Package	Marking
ASA65R1K4E	TO220F	ASA65R1K4E
ASU65R1K4E	TO251	ASU65R1K4E
ASD65R1K4E	TO252	ASD65R1K4E



1 Maximum ratings

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current ¹⁾	I_D		-	4	A	$T_C=25^\circ\text{C}$
Pulsed drain current ²⁾	$I_{D,\text{pulse}}$	-	-	12	A	$T_C=25^\circ\text{C}$
Avalanche energy, single pulse	E_{AS}	-	-	125	mJ	$T_C=25^\circ\text{C}$, $V_{DD}=50\text{V}$, $L=10\text{mH}$, $R_G=25\Omega$
MOSFET dv/dt ruggedness	dv/dt	-	-	50	V/ns	$V_{DS}=0\ldots 400\text{V}$
Gate source voltage (static)	V_{GS}	-20	-	20	V	static;
Gate source voltage (dynamic)	V_{GS}	-30	-	30	V	AC ($f > 1 \text{ Hz}$)
Power dissipation	P_{tot}	-	-	28	W	$T_C=25^\circ\text{C}$
Storage temperature	T_{stg}	-55	-	150	°C	
Operating junction temperature	T_j	-55	-	150	°C	
Reverse diode dv/dt ³⁾	dv/dt	-	-	15	V/ns	$V_{DS}=0\ldots 400\text{V}$, $I_{SD} \leq I_S$, $T_j = 25^\circ\text{C}$; see table 8

¹⁾ Limited by $T_{j,max}$. Maximum Duty Cycle D = 0.50

²⁾ Pulse width t_p limited by $T_{j,max}$

³⁾ Identical low side and high side switch with identical R_G

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2 Thermal characteristics

Table 3 Thermal characteristics (T0220 FullPAK)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	5.2	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	62.5	°C/W	device on PCB, minimal footprint

Thermal characteristics (T0251 and T0252)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	4.4	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	62	°C/W	device on PCB, minimal footprint

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3 Electrical characteristics

at $T_j=25^\circ\text{C}$, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	655	-	-	V	$V_{\text{GS}}=0\text{V}, I_D=10\text{mA}$
Gate threshold voltage	$V_{(\text{GS})\text{th}}$	2.5		4.5	V	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$
Zero gate voltage drain current	I_{DSS}	-	-	100	nA	$V_{\text{DS}}=650\text{V}, V_{\text{GS}}=0\text{V}, T_j=25^\circ\text{C}$
Gate-source leakage current	I_{GSS}	-	-	100	nA	$V_{\text{GS}}=30\text{V}, V_{\text{DS}}=0\text{V}$
Drain-source on-state resistance	$R_{\text{DS}(\text{on})}$	-	1.24	1.4	Ω	$V_{\text{GS}}=10\text{V}, I_D=2\text{A}, T_j=25^\circ\text{C}$
Gate resistance	R_G	-	13.4	-	Ω	f=1MHz, open drain

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	238	-	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=10\text{kHz}$
Output capacitance	C_{oss}	-	25	-	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=10\text{kHz}$
Reverse transfer capacitance	C_{rss}		4.2		pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=10\text{kHz}$
Turn-on delay time	$t_{d(\text{on})}$	-	5.2	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_D=1.2\text{A}, R_G=10\Omega$; see table 9
Rise time	t_r	-	22	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_D=1.2\text{A}, R_G=10\Omega$; see table 9
Turn-off delay time	$t_{d(\text{off})}$	-	30.4	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_D=1.2\text{A}, R_G=10\Omega$; see table 9
Fall time	t_f	-	25.2	-	ns	$V_{\text{DD}}=400\text{V}, V_{\text{GS}}=13\text{V}, I_D=1.2\text{A}, R_G=10\Omega$; see table 9

Table 6 Gate charge characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	0.4	-	nC	$V_{\text{DD}}=400\text{V}, I_D=1.2\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$
Gate to drain charge	Q_{gd}	-	1.5	-	nC	$V_{\text{DD}}=400\text{V}, I_D=1.2\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$
Gate charge total	Q_g	-	5.76	-	nC	$V_{\text{DD}}=400\text{V}, I_D=1.2\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$
Gate plateau voltage	V_{plateau}	-	4.2	-	V	$V_{\text{DD}}=400\text{V}, I_D=1.2\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$

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Table 7 Reverse diode characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	V_{SD}	-	0.79	-	V	$V_{GS}=0V$, $I_F=1A$, $T_j=25^\circ C$
Reverse recovery time	t_{rr}	-	158	-	ns	$V_R=400V$, $I_F=49.6A$, $di_F/dt=100A/\mu s$; see table 8
Reverse recovery charge	Q_{rr}	-	0.412	-	uC	$V_R=400V$, $I_F=49.6A$, $di_F/dt=100A/\mu s$; see table 8
Peak reverse recovery current	I_{rrm}	-	5.92	-	A	$V_R=400V$, $I_F=49.6A$, $di_F/dt=100A/\mu s$; see table 8

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4 Electrical characteristics diagram

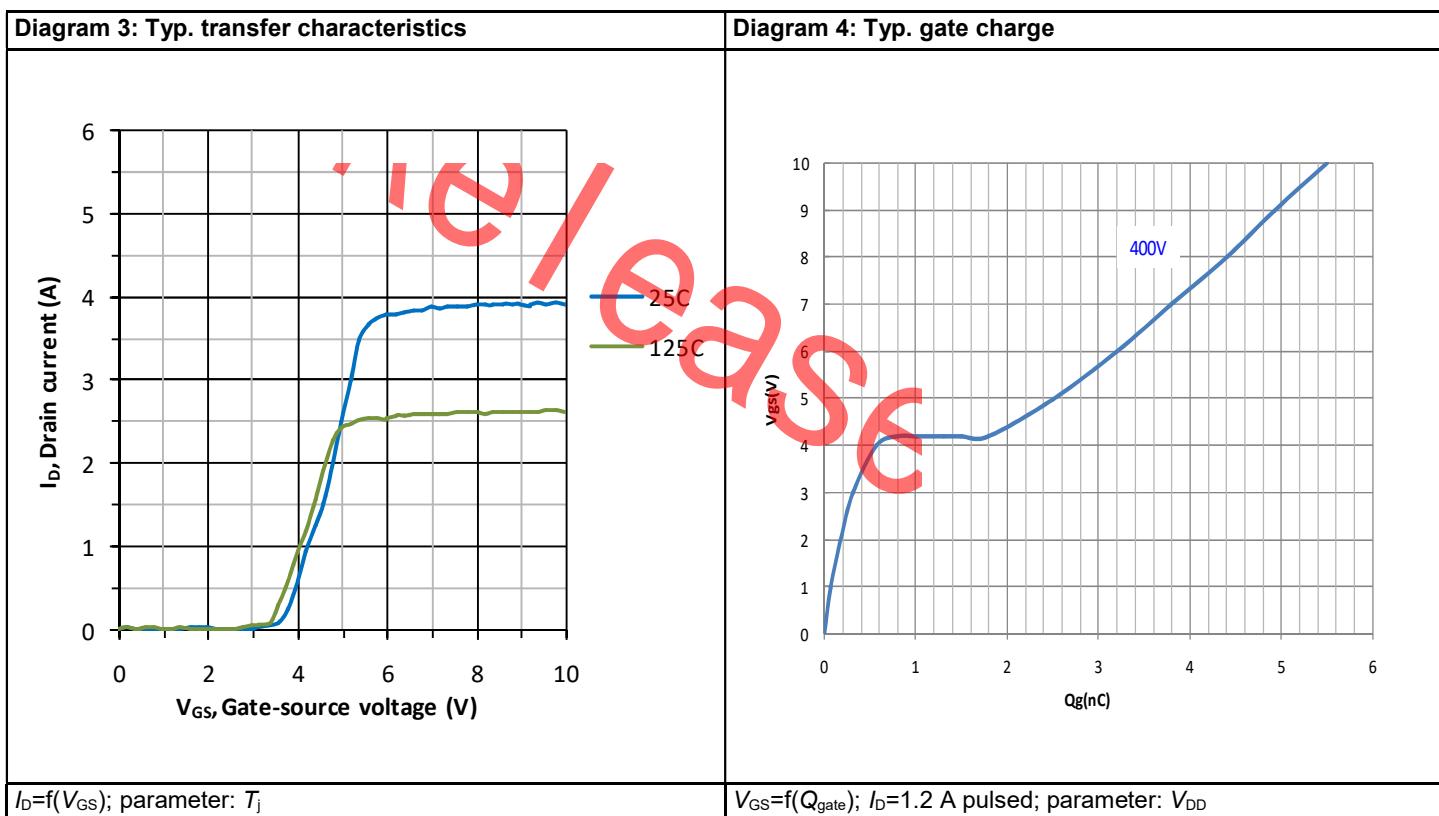
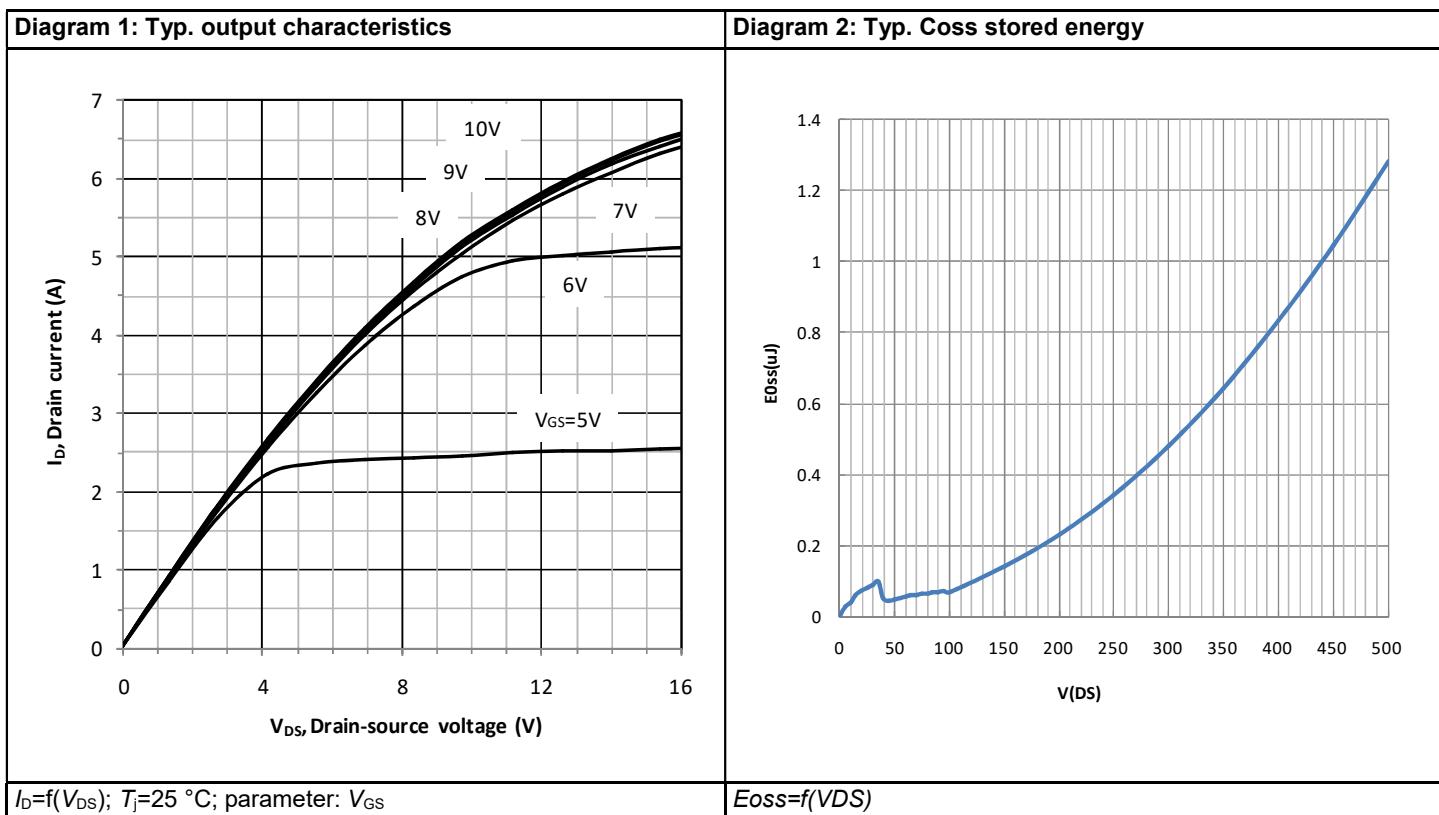


Diagram 5: Drain-source breakdown voltage

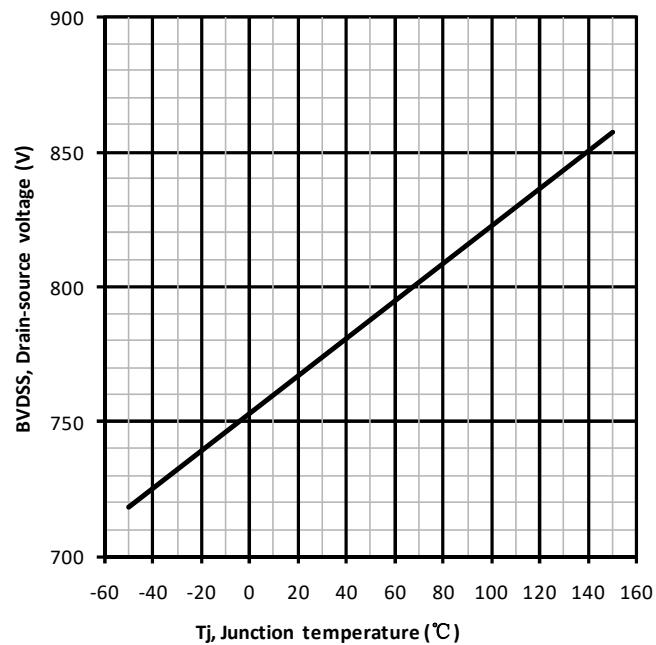
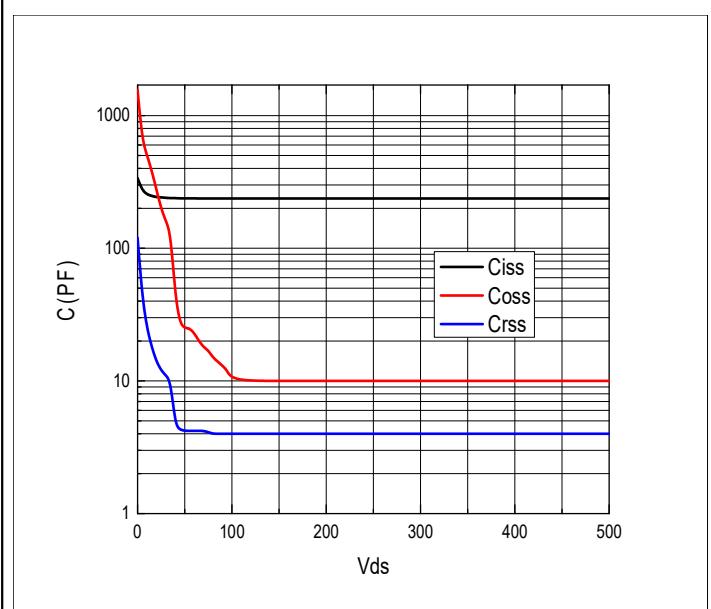


Diagram 6: Typ. capacitances

 $V_{BR(DSS)} = f(T_j); I_D = 10 \text{ mA}$ $C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 10 \text{ kHz}$

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5 Test Circuits

Table 8 Diode characteristics

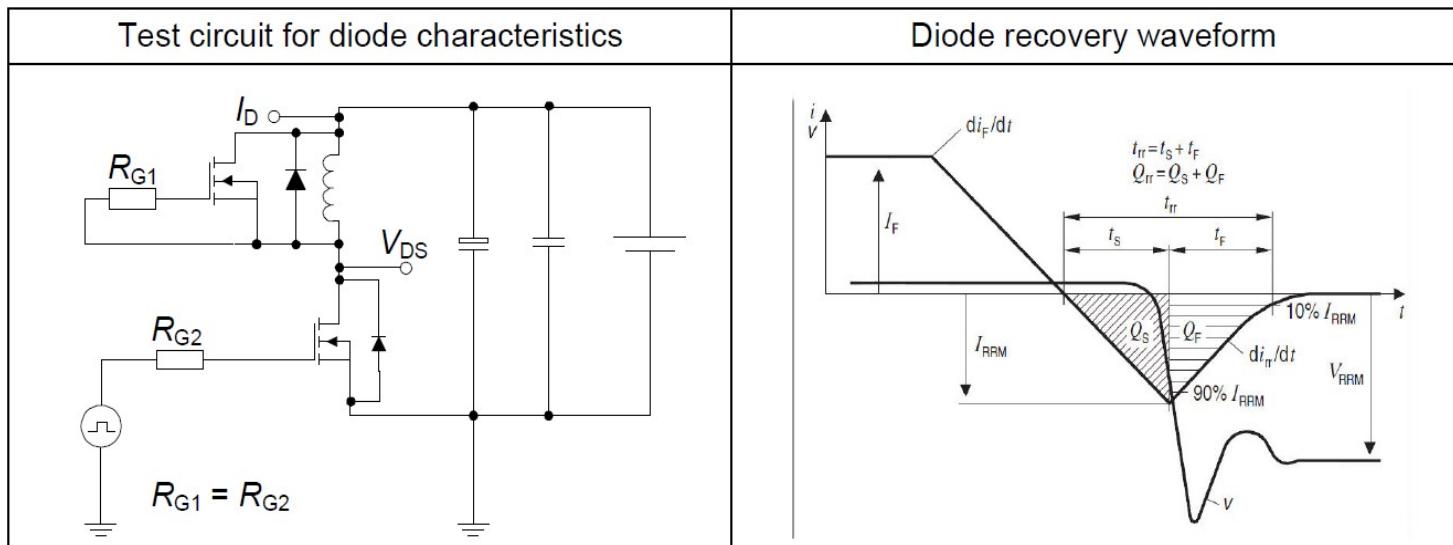


Table 9 Switching times

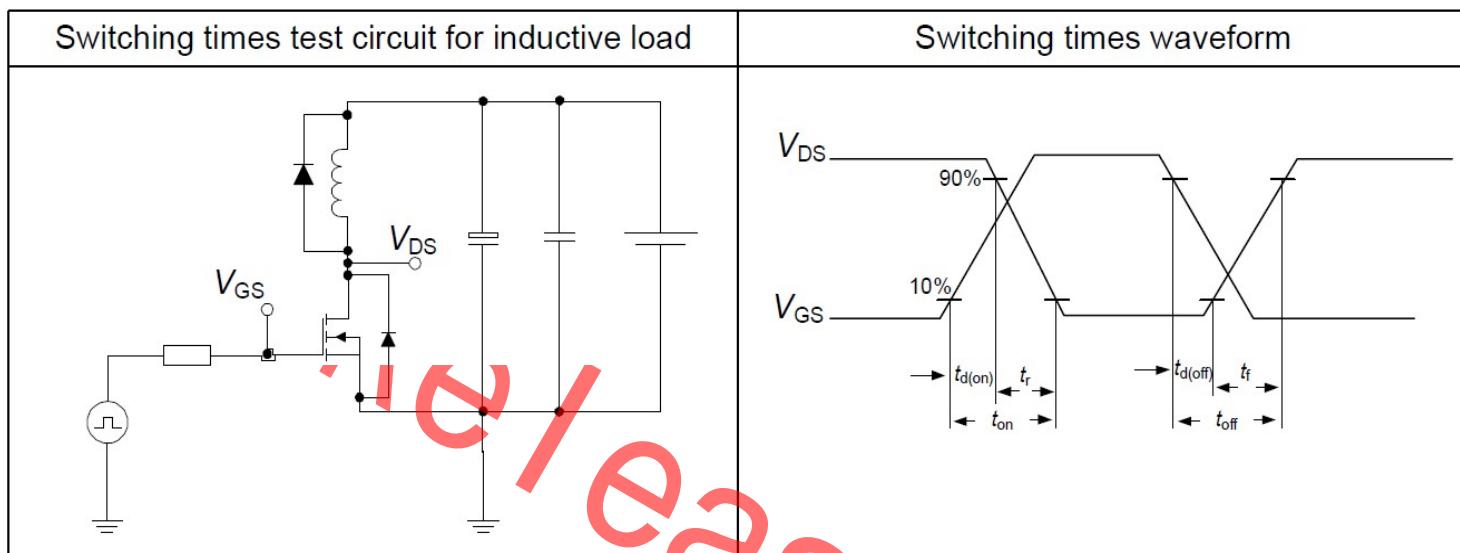
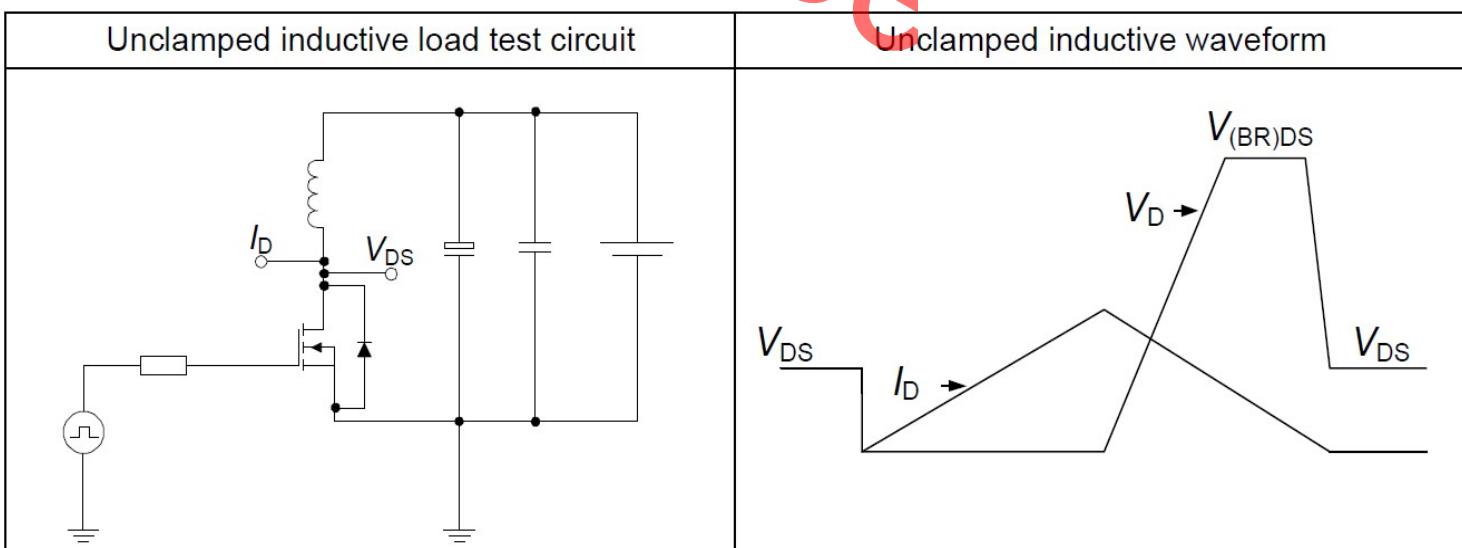


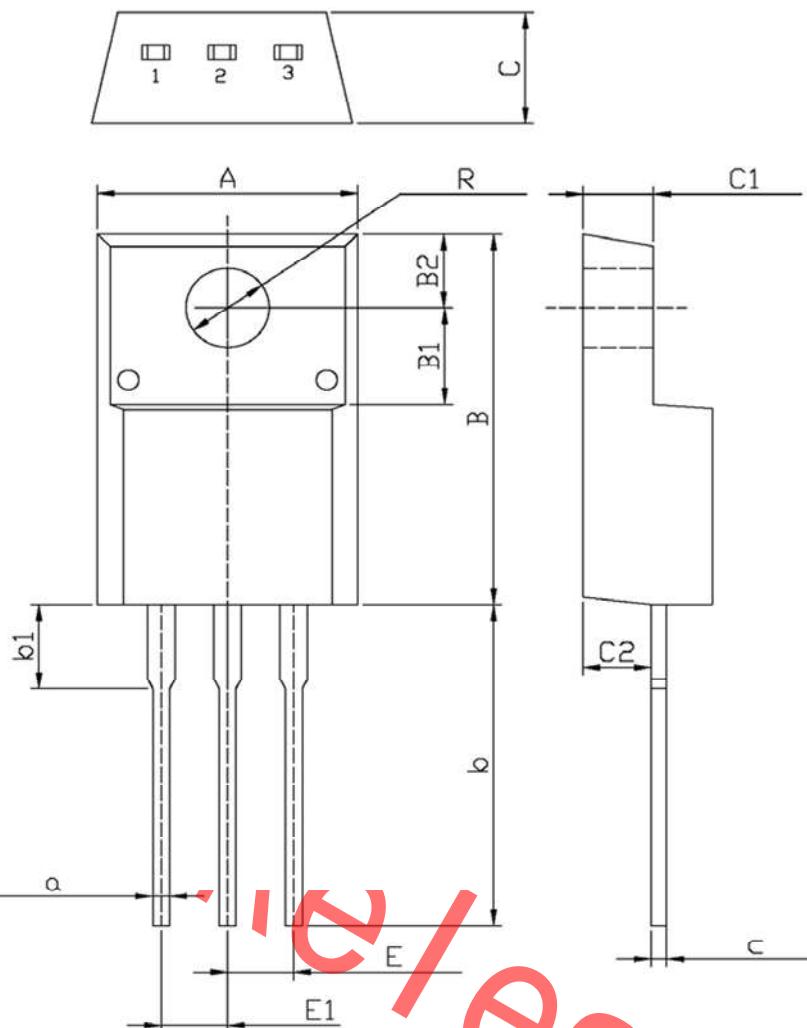
Table 10 Unclamped inductive load



6 Package Outlines

T□-220F

单位: mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
C	4.3	4.8	b1	2.9	3.9
A	9.7	10.3	a	0.55	0.9
B	14.7	16.1	E	2.29	2.79
B1	3.8	4	E1	2.29	2.79
B2	2.9	3.55	C1	2.5	2.9
R	3	3.4	C2	2.15	2.7
b	12.5	13.6	c	0.4	0.7

Figure1: Outline PG-T0220F

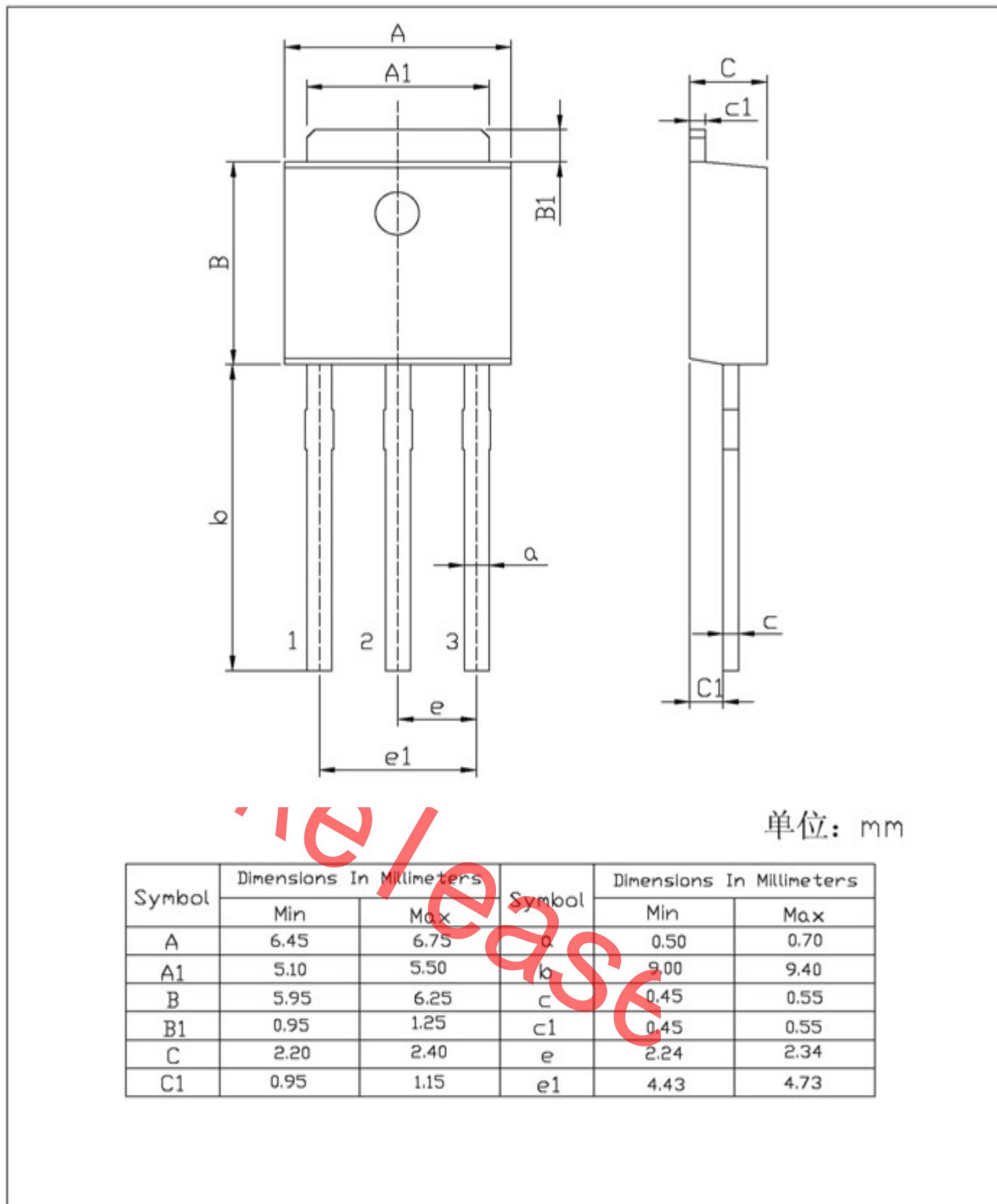
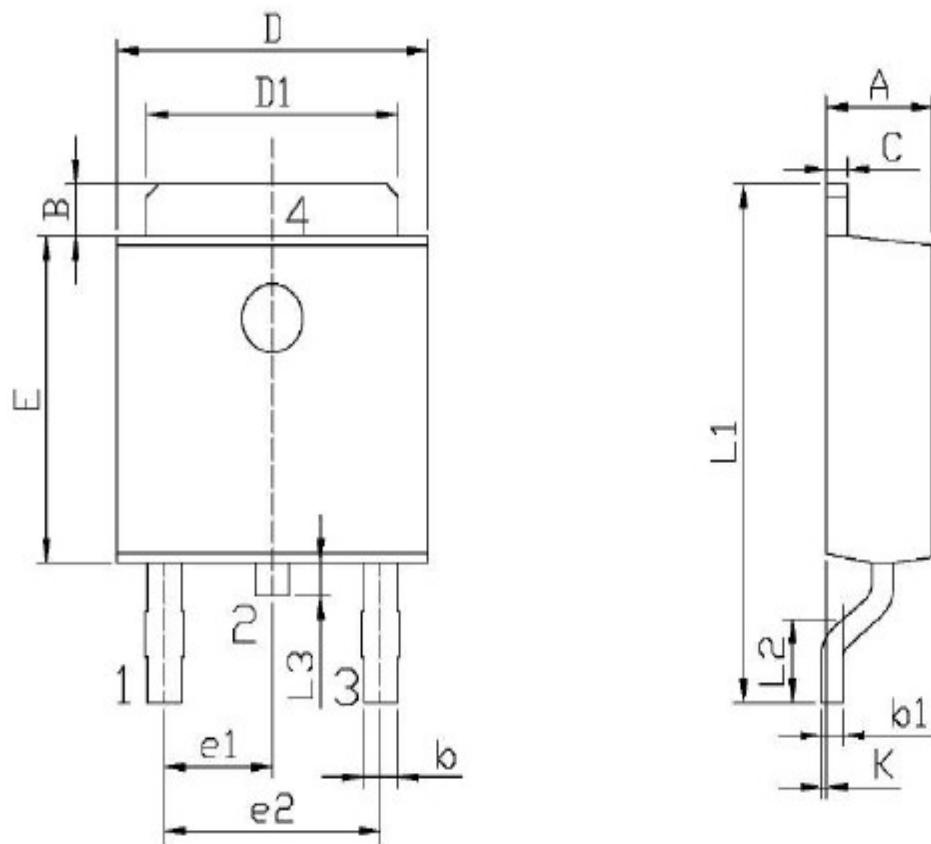


Figure2: Outline PG-T0251



单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	2.20	2.40	E	5.95	6.25
B	0.95	1.25	e1	2.24	2.34
b	0.50	0.70	e2	4.43	4.73
b1	0.45	0.55	L1	9.45	9.95
C	0.45	0.55	L2	1.25	1.75
D	6.45	6.75	L3	0.60	0.90
D1	5.10	5.50	K	0.00	0.10

Figure3: Outline PG-T0252

Revision History

Revision	Date	Subjects (major changes since last revision)
1.0	2020-07-15	Preliminary version

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